Product Change Notification

103266 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geography location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: **103266 - 00**

Change Title: **Intel® 0.13 Micron TSOP 32MB Advanced & Advanced+ Boot Block Flash Memory, PCN 103266-00, FFF**

Date of Publication: **April 24, 2003**

Type of Change Notification:

FFF - (Form-Fit-Function)

Key Characteristics of the Change:

Process

Forecasted Key Milestones:

Date of Samples Availability:	May 12, 2003
Date of Qualification Data Availability:	Jul 08, 2003
Date Customer Must be Ready to Receive Post-Conversion Material:	Aug 11, 2003
Date of First Availability of Post-Conversion Material:	Aug 11, 2003

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Intel is proliferating the Intel® 32 Mb TSOP Advanced & Advanced+ Boot Block Flash Memory product to its new 0.13µm lithography.

This will improve product availability, and increase production capacity across Intel's wafer and assembly fabrication network. This will also enable Intel to more effectively respond to the growing demands for Flash.

Customer Impact of Change and Recommended Action:

Intel does not anticipate any impact to customer applications. The TSOP Advanced & Advanced+ Boot Block Flash Memory product on 0.13µm lithography will meet Intel's quality and reliability standards and is backwards compatible with Intel's current Advanced & Advanced+ Boot Block Flash Memory products on 0.18µm lithography.

This Product Change Notification is for TSOP only. EASY-BGA and VFBGA have already converted to 0.13µm. TSOP package is backward compatible to current generation Advanced and Advanced+ Boot Block Flash memory product line.

In addition to this process lithography proliferation, Intel will also be modifying the part number for the 0.13µm lithography version of the product so customers may differentiate 0.18µm lithography products from 0.13µm lithography products. (Ref: Products Affected table below)

The TSOP package will exhibit a part marking change, with the new 0.13µ process designator "D" replacing the 0.18µ process designator "C".

Customers must be positioned to accept and use 0.13µm lithography products interchangeably with current 0.18µm lithography Advanced & Advanced+ Boot Block Flash Memory products.

Products Affected / Intel Ordering Codes:

32Mb TSOP Products Subject to Conversion

Pre-Conversion Product Code	Pre-Conversion Spec/ROM	Pre-Conversion MM#
TE28F320C3TC90 S B48	S B48	833357
TE28F320C3BC90 S B48	S B48	833358
TE28F320B3TC90 S B48	S B48	833360
TE28F320B3BC90 S B48	S B48	833361
TE28F320C3TC70 S B48	S B48	833362
TE28F320C3BC70 S B48	S B48	833363
TE28F320B3TC70 S B48	S B48	833365
TE28F320B3BC70 S B48	S B48	833366
TE28F320C3TC90 833376		833376
TE28F320C3BC90 833377		833377
TE28F320B3TC90 833378		833378
TE28F320B3BC90 833379		833379
TE28F320B3BC70 833385		833385
TE28F320B3TC70 833386		833386
TE28F320C3BC70 833387		833387
TE28F320C3TC70 833388		833388

32Mb TSOP .13 Micron Samples

Sample Product Code	Sample Spec/ROM	Sample MM#	Description
TE28F320B3BD70 Q R49	Q R49	854177	100pc Tape & Reel
TE28F320B3BD70 Q R52	Q R52	854180	2 pc Tube
TE28F320B3TD70 Q R50	Q R50	854178	100pc Tape & Reel
TE28F320B3TD70 Q R51	Q R51	854179	2 pc Tube
TE28F320C3BD70 Q R54	Q R54	854182	100pc Tape & Reel
TE28F320C3BD70 Q R56	Q R56	854184	2 pc Tube
TE28F320C3TD70 Q R53	Q R53	854181	100pc Tape & Reel
TE28F320C3TD70 Q R55	Q R55	854183	2 pc Tube